

Nch 100V 20A Power MOSFET

V_{DSS}	100V
R _{DS(on)} (Max.)	46m $Ω$
I _D	20A
P_D	20W

● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

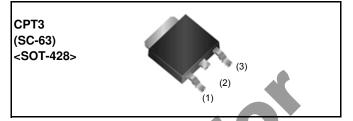
Application

Switching Power Supply

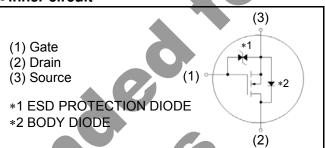
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	201N10

• Absolute maximum ratings($T_a = 25^{\circ}C$)

Parameter		Symbol	Value	Unit
Drain - Source voltage		$V_{ m DSS}$	100	V
Continuous drain current	T _c = 25°C	I _D *1	±20	А
Continuous urain current	T _c = 100°C	I _D *1	±10	А
Pulsed drain current	I _{D,pulse} *2	±80	А	
Gate - Source voltage	V_{GSS}	±20	V	
Avalanche energy, single pulse	E _{AS} *3	14.6	mJ	
Avalanche current		I _{AR} *3	10	А
Device dischartion	T _c = 25°C	P_{D}	20	W
Power dissipation $T_a = 25^{\circ}C$		P_{D}	0.85	W
Junction temperature	T _j	150	°C	
Range of storage temperature		T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Зуппоп	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	6.25	°C/W

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Symbol Conditions -		Values		
r arameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	100		-	V
		V _{DS} = 100V, V _{GS} = 0V			1	
Zara gata valtaga drain augrant	ı	T _j = 25°C		-	1	۸
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V			100	μΑ
		T _j = 125°C	-	Y	100	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$		-	±10	μА
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	1.0	-	2.5	V
		$V_{GS} = 10V, I_D = 20A$		33	46	
Static drain - source	D *4	$V_{GS} = 4.0V, I_D = 20A$	-	36	50	m()
on - state resistance	R _{DS(on)} *4	$V_{GS} = 10V, I_D = 20A$	_	60	84	mΩ
		T _j = 125°C				
Forward transfer admittance	g _{fs}	$V_{DS} = 10V, I_{D} = 20A$	15	30	-	S



●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii etei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	V _{GS} = 0V	-	2100	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	180	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	120		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 50V$, $V_{GS} = 10V$	-	100		
Rise time	t _r *4	I _D = 10A	-	35	-	no
Turn - off delay time	t _{d(off)} *4	$R_L = 12\Omega$	- (150	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-7/	100	-	

●Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii etei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*4}	V _{DD} ≃ 50V	C	55	-	
Gate - Source charge	Q _{gs} *4	I _D = 20A	-	5.5	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 10V	-	12.5	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} \simeq 30V$, $I_D = 20A$	-	2.7	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter Symb		Conditions	Values			Unit
Parameter	Syllibol	ymbol Conditions —		Тур.	Max.	Offic
Continuous source current	l _S *1	T _c = 25°C	-	-	14	Α
Pulsed source current	I _{SM} *2	1 _c = 25 C	-	-	80	Α
Forward voltage	V_{SD}^{*4}	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V
Reverse recovery time	t _{rr} *4	I _S = 20A	-	65	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	144	1	μС

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L \simeq 100 μ H, V_{DD} = 50V, Rg = 10 Ω , starting T_j = 25°C

^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve

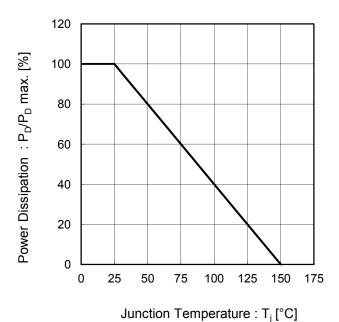
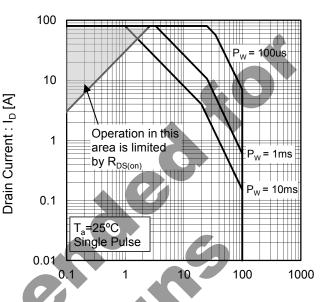
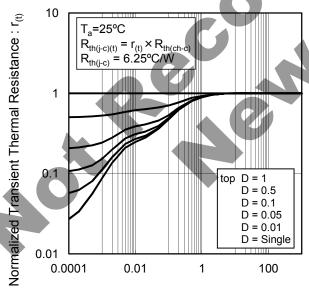


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

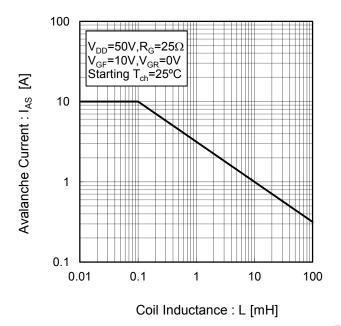
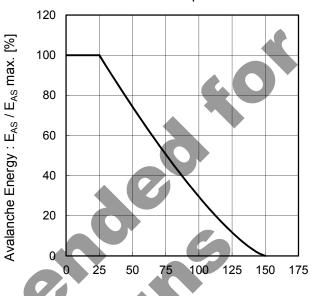


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)

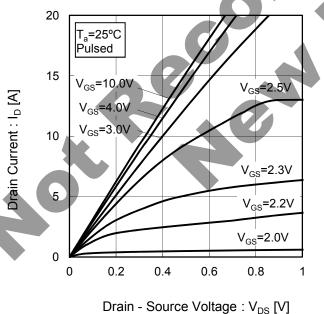
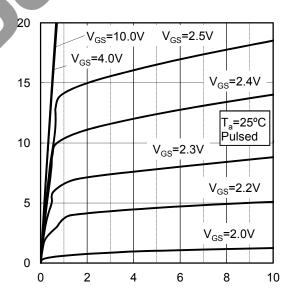


Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

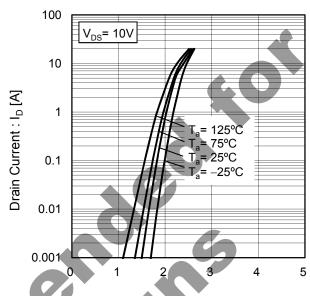
Drain Current : I_D [A]

-50

Fig.8 Breakdown Voltage vs. Junction Temperature 120 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 115 $I_D = 1mA$ 110 105 $:V_{(BR)DSS}[V]$ 100 95 90 85 80

0

Fig.9 Typical Transfer Characteristics



Gate - Source Voltage : V_{GS} [V]

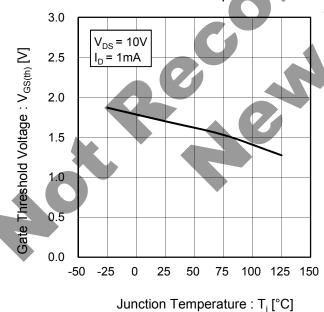
Fig.10 Gate Threshold Voltage vs. Junction Temperature

50

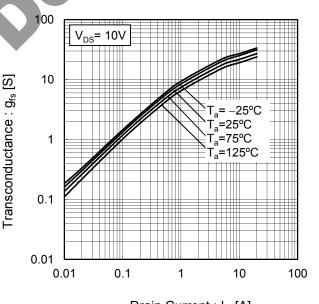
Junction Temperature : T_i [°C]

100

150



Transconductance vs. Drain Current



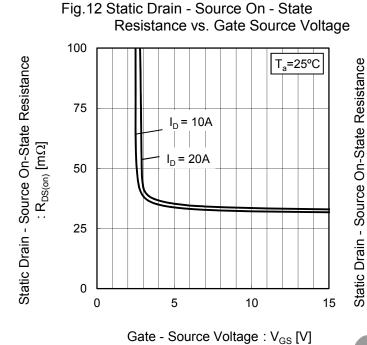
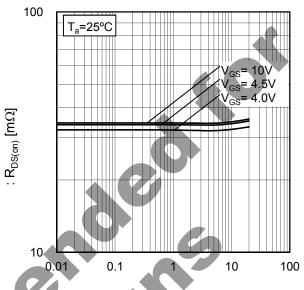
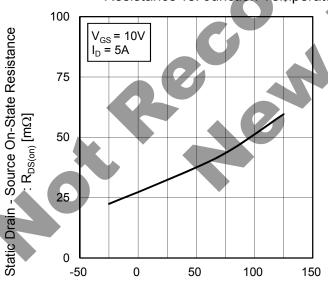


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)



Drain Current : I_D [A]

Fig.14 Static Drain - Source On - State
Resistance vs. Junction Temperature



Junction Temperature : T_j [°C]

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

1000 $V_{GS} = 10V$ $T_a = 125^{\circ}C$ $T_a = 75^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$ Drain Current : I_D [A]

Drain Current : I_D [A]

Fig.17 Static Drain - Source On - State
Resistance vs. Drain Current(IV)

Ta=125°C
Ta=75°C
Ta=25°C
Ta=25°C
Ta=25°C
Ta=25°C
Ta=25°C
Ta=25°C
Ta=25°C
Ta=25°C
Ta=125°C
T

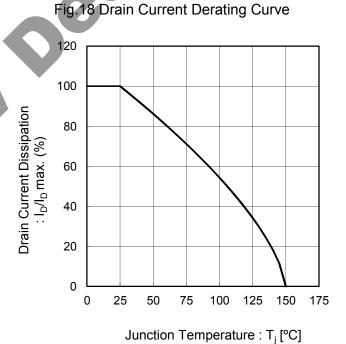
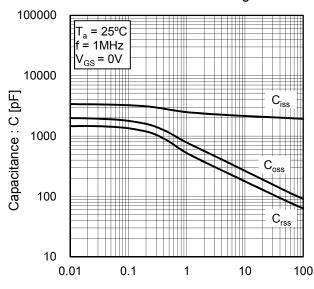
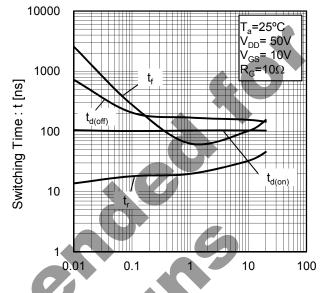


Fig.19 Typical Capacitance vs. Drain - Source Voltage



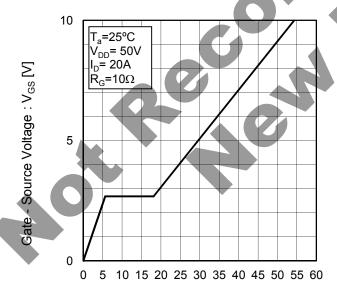
Drain - Source Voltage : V_{DS} [V]

Fig.20 Switching Characteristics



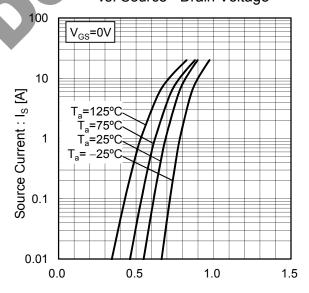
Drain Current : I_D [A]

Fig.21 Dynamic Input Characteristics

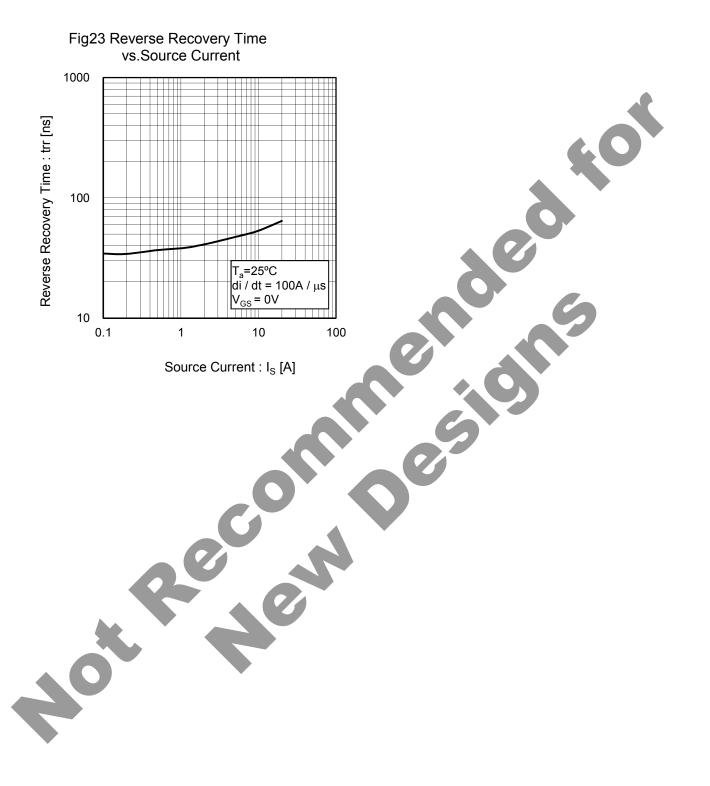


Total Gate Charge : Q_g [nC]

Fig.22 Source Current vs. Source - Drain Voltage



Source-Drain Voltage : V_{SD} [V]



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

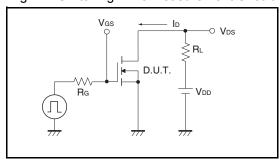


Fig.2-1 Gate Charge Measurement Circuit

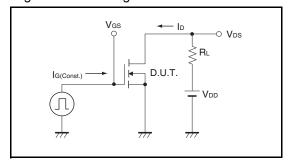


Fig.3-1 Avalanche Measurement Circuit

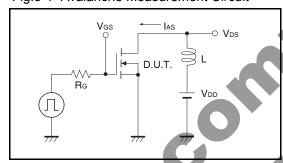


Fig.1-2 Switching Waveforms

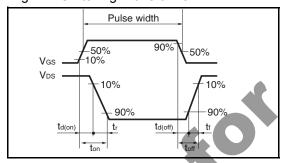


Fig.2-2 Gate Charge Waveform

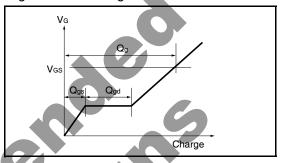
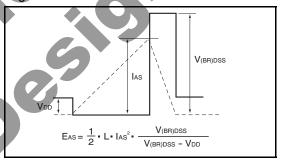
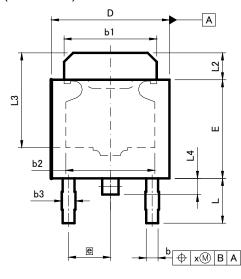


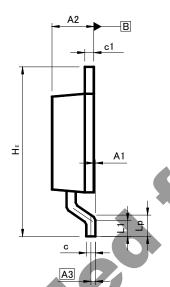
Fig.3-2 Avalanche Waveform

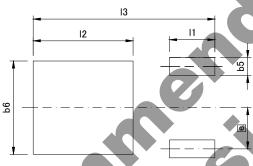


● **Dimensions** (Unit: mm)









DIM	MILIM	ETER\$	INC	HES	
DIM	MIN	MAX	MIN	MAX	
A1	0.00	0.15	0	0.006	
A2	2,20	2.50	0.087	0.098	
A3	0.2	25	0.0	01	
b	0.55	0.75	0.022	0.03	
b1	5.00	5.30	0.197	0.209	
b2	5.0	00	0.3	20	
b3	0.	75	0.0	03	
С	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.30	6.70	0.248	0.264	
E	5.40	5.80	0.213	0.228	
е	2.3	30	0.09		
HE	9.00	10.00	0.354	0.394	
L	2.20	2.80	0.087	0.11	
L1	0.80	1.40	0.031	0.055	
L2	1.20	1.80	0.047	0.071	
L3	5.30		0.209		
L4	0.9	0.90		35	
Lp	1.00	1.60	0.039	0.063	
х	_	0.25	_	0.01	

DIM MILIME		ETERS	INC	INCHES	
DIM	MIN	MAX	MIN	MAX	
b5	_	1.00	ı	0.04	
b6	_	5.20	-	0.205	
l1	-	2.50	-	0.098	
12	_	5.50	-	0.217	
13	_	10.00	_	0.394	

Dimension in mm/inches

Notice

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIT
CLASSIV	CLASSIII	CLASSⅢ	CLASSII

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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